

**AMENDMENTS TO THE SPECIFICATION**

**Please delete the present Abstract of the Disclosure.**

**Please add the following new Abstract of the Disclosure:**

The invention provides a A-multilayer wiring board including~~comprises~~ a metal substrate having first and second main surfaces, a copper coating applied to at least one of the first and second main surfaces of the metal substrate and having a roughened surface, and an insulating resin layer formed on the roughened surface of the copper coating. The multilayer wiring board may further include~~comprises~~ a wiring layer arranged on the insulating resin layer and a via extending through the insulating resin layer between the copper coating and the wiring layer.